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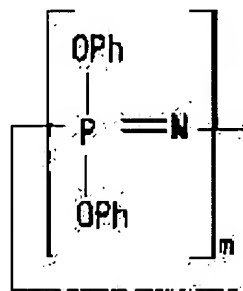
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## (54) HEAT RESISTANT COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To obtain a halogen free polyimide-based resin composition having solubility in a low boiling point solvent, heat resistance, flame retardant property, adhesive force and dynamic characteristics simultaneously.

SOLUTION: This heat resistant composition contains (A) a solvent soluble polyimide-based resin and (B) a following phosphazene compound, and the phosphazene compound (B) is a cyclic phenoxyphosphazene compound (B1) expressed by formula (1) [wherein, (m) is 3-25 integer; and Ph is phenyl].



(1)

## LEGAL STATUS

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